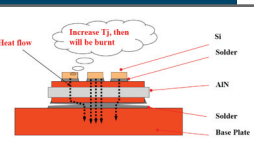
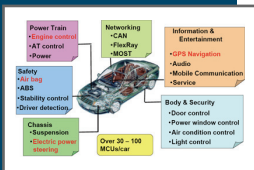
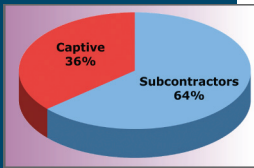
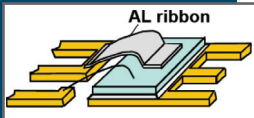
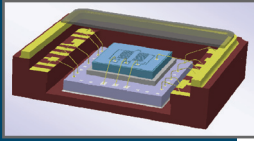


Advanced Packaging Update: Market and Technology Trends

Vol. 4-010



This issue of the Advanced Packaging Update features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The BGA market is divided into plastic, tape, and ceramic structures. The CSP market is divided into laminate, flex circuit, and leadframe substrates. Unit growth projections for shipments of stacked die CSP, package-on-package (PoP), and package-in-package (PiP) are provided. Estimates of the market for each package type are based on input from both captive and merchant assembly operations. Key applications and drivers for unit volume growth are highlighted. An analysis of the impact of the tragic events in Japan on the electronics industry infrastructure is also included. A special section provides insights into automotive packaging.

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